



钜地半导体  
Tudi Semiconductor

## Product Specification

24LC256T-I/SN-TUDI

256K I<sup>2</sup>C™ CMOS Serial EEPROM

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## Device Selection Table

| Part Number | Vcc Range | Max. Clock Frequency   | Temp. Ranges |
|-------------|-----------|------------------------|--------------|
| 24AA256     | 1.8-5.5V  | 400 kHz <sup>(1)</sup> | I            |
| 24LC256     | 2.5-5.5V  | 400 kHz                | I            |
|             |           |                        |              |

Write:

Byte Write within 3ms

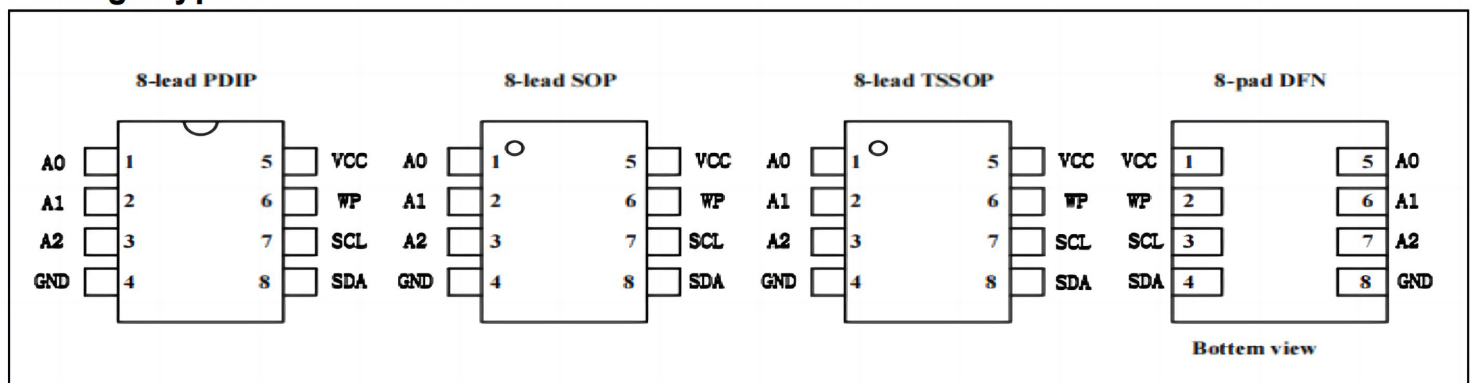
Page Write within 3ms

- 2-wire serial interface bus, I<sup>2</sup>C<sup>™</sup> compatible
- Cascadable for up to eight devices
- Self-timed erase/write cycle
- 64-byte Page Write mode available
- Hardware write-protect for entire array
- Schmitt Trigger inputs for noise suppression
- 1,000,000 erase/write cycles
- Electrostatic discharge protection > 4000V
- Data retention > 200 years
- 8-pin PDIP, SOIC, TSSOP, MSOP and DFN
- Pb-free finishes available

## Description:

24AA256/24LC256/ (24XX256\*) is a 32K x 8 (256 Kbit) SerialElectrically Erasable PROM, capable of operation across a broad voltage range (1.8V to 5.5V). It has been developed for advanced, low-power applications such as personal communications or data acquisition. This device also has a page write capability of up to 64 bytes of data. This device is capable of both random and sequential reads up to the 256K boundary. Functional address lines allow up to eight devices on the same bus, for up to 2 Mbit address space. This device is available in the standard 8-pin plastic DIP, SOIC, TSSOP, MSOP and DFN packages.

## Package Types





## Pin Descriptions

| Pin Name | Type | Functions          |
|----------|------|--------------------|
| A0-A2    | I    | Address Inputs     |
| SDA      | I/O  | Serial Data        |
| SCL      | I    | Serial Clock Input |
| WP       | I    | Write Protect      |
| GND      | P    | Ground             |
| Vcc      | P    | Power Supply       |

Table 1

## Block Diagram

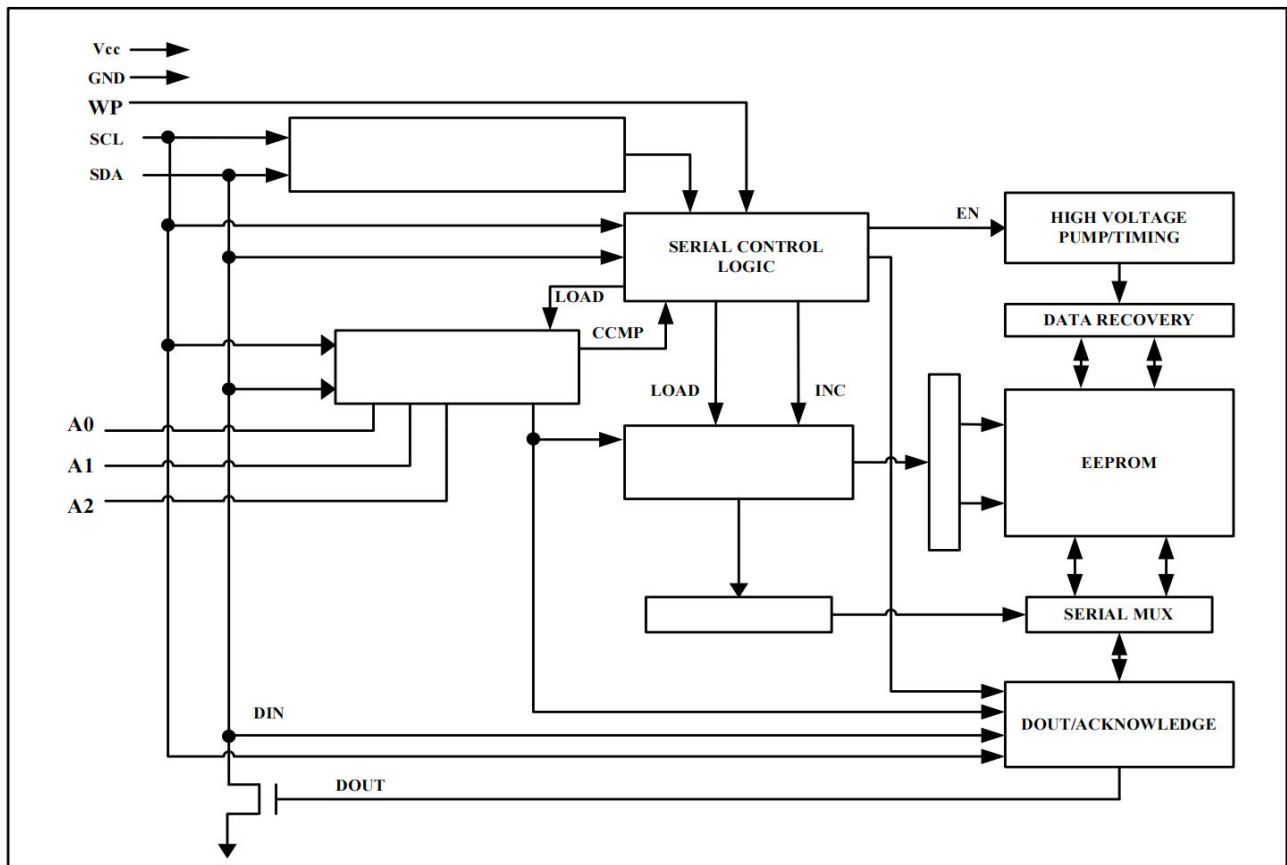


Figure 1

**DEVICE/PAGE ADDRESSES (A2, A1 and A0):** The A2, A1 and A0 pins are device address inputs that are hard wire for the 24AA256/24LC256 . Eight 256K devices may be addressed on a single bus system (device addressing is discussed in detail under the Device Addressing section).

**SERIAL DATA (SDA):** The SDA pin is bi-directional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or open- collector devices.

**SERIAL CLOCK (SCL):** The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.



**WRITE PROTECT (WP):** The 24AA256/24LC256 has a Write Protect pin that provides hardware data protection. The Write Protect pin allows normal read/write operations when connected to ground (GND). When the Write Protection pin is connected to Vcc, the write protection feature is enabled and operates as shown in the following **Table 2**.

| WP Pin Status | 24AA256/24LC256              |
|---------------|------------------------------|
| At VCC        | Full(256K)Array              |
| At GND        | Normal Read/Write Operations |

Table 2

## Functional Description

### 1. Memory Organization

**24AA256/24LC256 , 256K SERIAL EEPROM:** Internally organized with 256 pages of 64 bytes each, the 256K requires a 15-bit data word address for random word addressing.

### 2. Device Operation

**CLOCK and DATA TRANSITIONS:** The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods (see **Figure 2**). Data changes during SCL high periods will indicate a start or stop condition as defined below.

**START CONDITION:** A high-to-low transition of SDA with SCL high is a start condition which must precede any other command (see **Figure 3**).

**STOP CONDITION:** A low-to-high transition of SDA with SCL high is a stop condition. After a read sequence, the stop command will place the EEPROM in a standby power mode (see **Figure 3**).

**ACKNOWLEDGE:** All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The EEPROM sends a "0" to acknowledge that it has received each word. This happens during the ninth clock cycle.

**STANDBY MODE:** The 24AA256/24LC256 features a low-power standby mode which is enabled: (a) upon power-up and (b) after the receipt of the STOP bit and the completion of any internal operations.

**MEMORY RESET:** After an interruption in protocol, power loss or system reset, any two-wire part can be reset by following these steps:

1. Clock up to 9 cycles.
2. Look for SDA high in each cycle while SCL is high.
3. Create a start condition.



Figure 2. Data

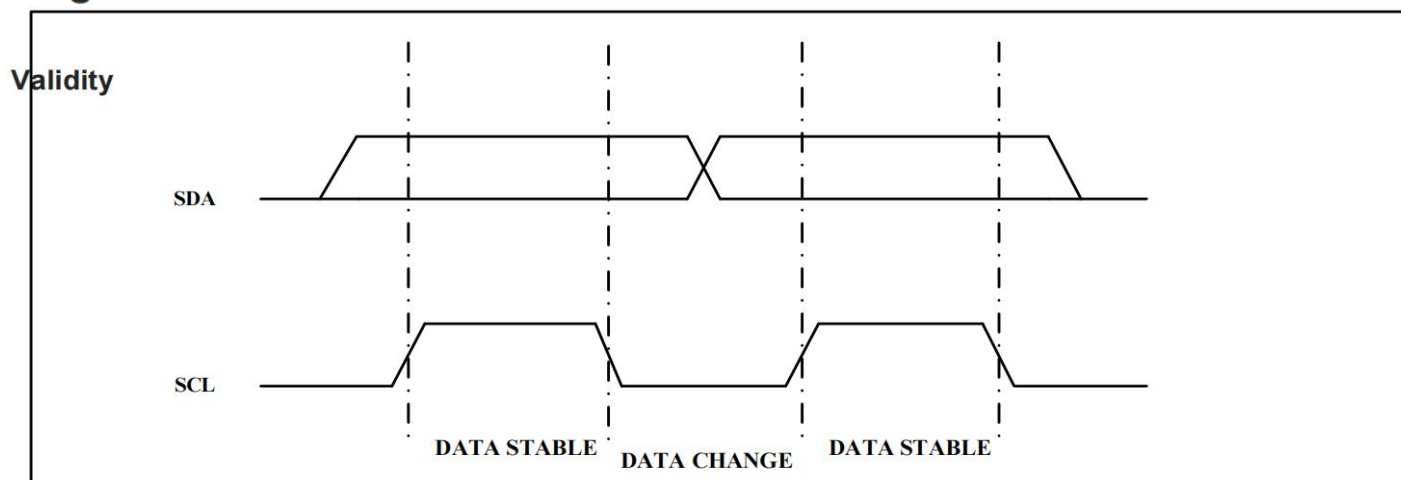


Figure 3. Start and Stop Definition

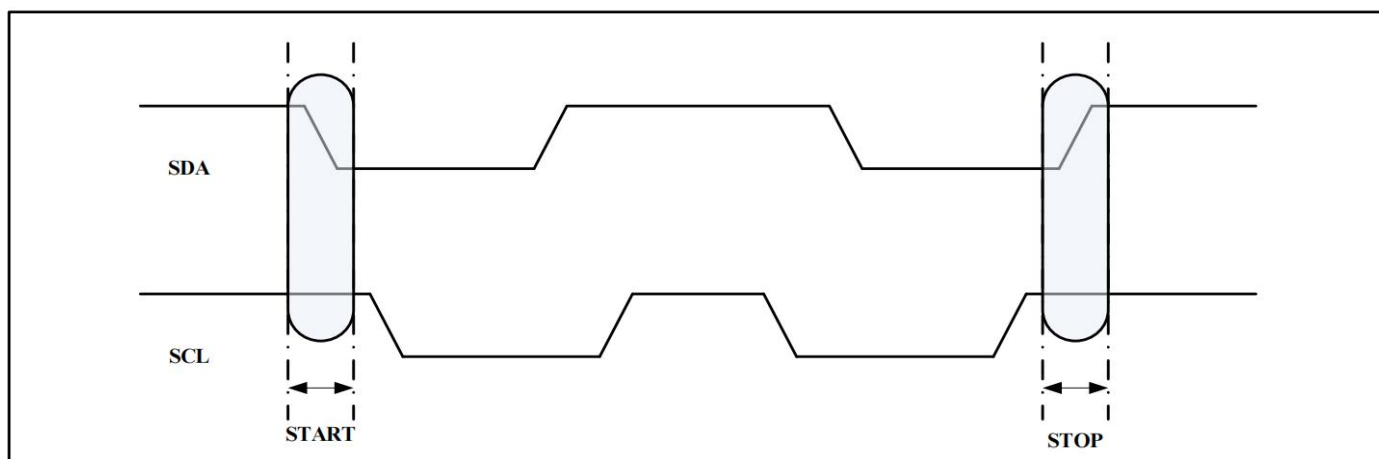
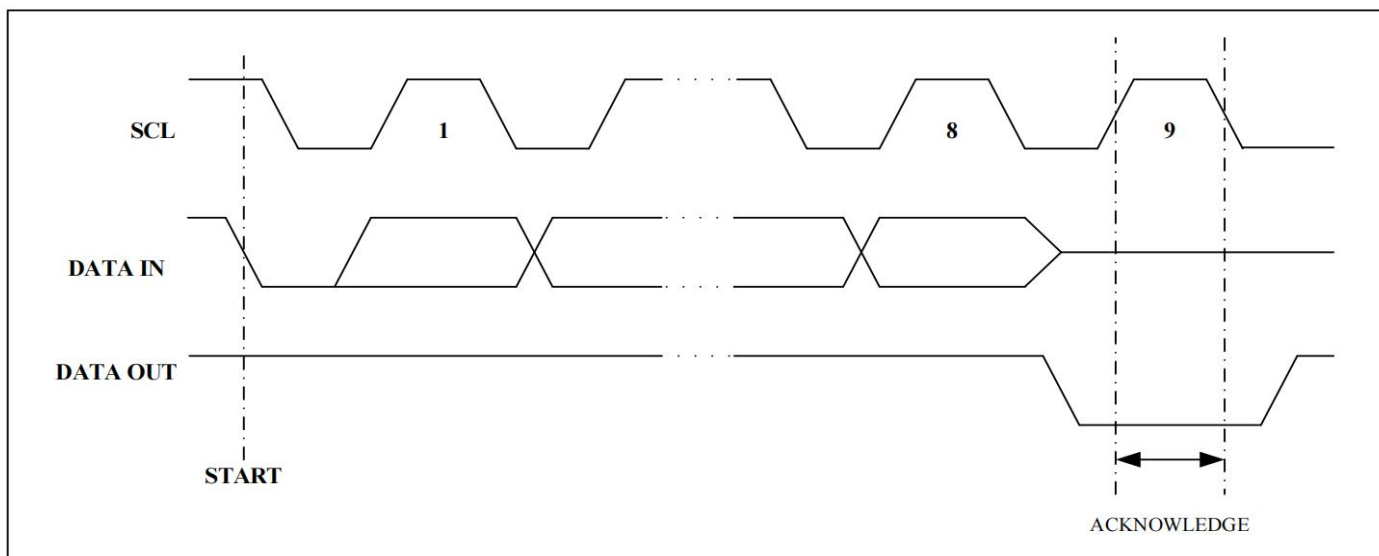


Figure 4. Output Acknowledge





### 3. Device Addressing

The 256K EEPROM devices all require an 8-bit device address word following a start condition to enable the chip for a read or write operation (see **Figure 5**)

The device address word consists of a mandatory "1", "0" sequence for the first four most significant bits as shown. This is common to all the Serial EEPROM devices.

The 256K EEPROM uses A2, A1 and A0 device address bits to allow as much as eight devices on the same bus. These 3 bits must be compared to their corresponding hardwired input pins. The A2, A1 and A0 pins use an internal proprietary circuit that biases them to a logic low condition if the pins are allowed to float.

The eighth bit of the device address is the read/write operation select bit. A read operation is initiated if this bit is high and a write operation is initiated if this bit is low.

Upon a compare of the device address, the EEPROM will output a "0". If a compare is not made, the chip will return to a standby state.

**DATA SECURITY:** The 24AA256/24LC256 has a hardware data protection scheme that allows the user to write protect the entire memory when the WP pin is at VCC.

### 4. Write Operations

**BYTE WRITE:** A write operation requires an 8-bit data word address following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a "0" and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a "0" and the addressing device, such as a microcontroller, must terminate the write sequence with a stop condition. At this time the EEPROM enters an internally timed write cycle,  $t_{WR}$ , to the nonvolatile memory. All inputs are disabled during this write cycle and the EEPROM will not respond until the write is complete (see **Figure 6**).

**PAGE WRITE:** A write operation requires an 8-bit data word address following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a "0" and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a "0" and the addressing device, such as a microcontroller, must terminate the write sequence with a stop condition. At this time the EEPROM enters an internally timed write cycle,  $t_{WR}$ , to the nonvolatile memory. All inputs are disabled during this write cycle and the EEPROM will not respond until the write is complete (see **Figure 7**).

The data word address lower five bits are internally incremented following the receipt of each data word. The higher data word address bits are not incremented, retaining the memory page row location. When the word address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than 64 data words are transmitted to the EEPROM, the data word address will "roll over" and previous data will be overwritten.

**WRITE IDENTIFICATION PAGE:** The Identification Page (64 bytes) is an additional page which can be written and (later) permanently locked in Read-only mode. It is written by issuing the Write



Identification Page instruction. This instruction uses the same protocol and format as Page Write (into memory array), except for the following differences:

- Device type identifier = 1011b
- MSB address bits B15/B6 are don't care except for address bit B10 which must be "0".

LSB address bits B5/B0 define the byte address inside the Identification page.

If the Identification page is locked, the data bytes transferred during the Write Identification Page instruction are not acknowledged (NoAck).

**ACKNOWLEDGE POLLING:** Once the internally timed write cycle has started and the EEPROM inputs are disabled, acknowledge polling can be initiated. This involves sending a start condition followed by the device address word. The read/write bit is representative of the operation desired. Only if the internal write cycle has completed will the EEPROM respond with a "0", allowing the read or write sequence to continue.

## 5. Read Operations

Read operations are initiated the same way as write operations with the exception that the read/write select bit in the device address word is set to "1". There are three read operations: current address read, random address read and sequential read.

### CURRENT ADDRESS READ:

The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the chip power is maintained. The address "roll over" during read is from the last byte of the last memory page to the first byte of the first page. The address "roll over" during write is from the last byte of the current page to the first byte of the same page. Once the device address with the read/write select bit set to "1" is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an input "0" but does generate a following stop condition (see **Figure 8**).

### RANDOM READ:

A random read requires a "dummy" byte write sequence to load in the data word address. Once the device address word and data word address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another start condition. The microcontroller now initiates a current address read by sending a device address with the read/write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a "0" but does generate a following stop condition (see **Figure 9**).

**SEQUENTIAL READ:** Sequential reads are initiated by either a current address read or a random address read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data word address and serially clock out sequential data words. When the memory address limit is reached, the data word address will "roll over" and the sequential read will continue. The sequential read operation is terminated when the



microcontroller does not respond with a "0" but does generate a following stop condition (see **Figure 10**).

**READ IDENTIFICATION PAGE:** The Identification Page (64 bytes) is an additional page which can be written and (later) permanently locked in Read-only mode.

The Identification Page can be read by issuing an Read Identification Page instruction. This instruction uses the same protocol and format as the Random Address Read (from memory array) with device type identifier defined as 1011b. The MSB address bits B15/B6 are don't care, the LSB address bits B5/B0 define the byte address inside the Identification Page. The number of bytes to read in the ID page must not exceed the page boundary (e.g.: when reading the Identification Page from location 10d, the number of bytes should be less than or equal to 22, as the ID page boundary is 64 bytes)

**LOCK IDENTIFICATION PAGE:** The Lock Identification Page instruction (Lock ID) permanently locks the Identification page in Read-only mode. The Lock ID instruction is similar to Byte Write (into memory array) with the following specific conditions:

Device type identifier = 1011b

Address bit B10 must be '1' ; all other address bits are don't care

The data byte must be equal to the binary value xxxx xx1x, where x is don't care

**Table 3. FIRST WORD ADDRESS**

| B15 | B14 | B13 | B12 | B11 | B10 | B9 | B8 |
|-----|-----|-----|-----|-----|-----|----|----|
|-----|-----|-----|-----|-----|-----|----|----|

**Table 4. SECOND WORD ADDRESS**

| B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|----|----|----|----|----|----|----|----|
|----|----|----|----|----|----|----|----|

**Figure 5. Device Address**

| MSB |   |   |   | LSB |    |    |     |
|-----|---|---|---|-----|----|----|-----|
| 1   | 0 | 1 | 0 | A2  | A1 | A0 | R/W |

**Figure 6. Byte Write**

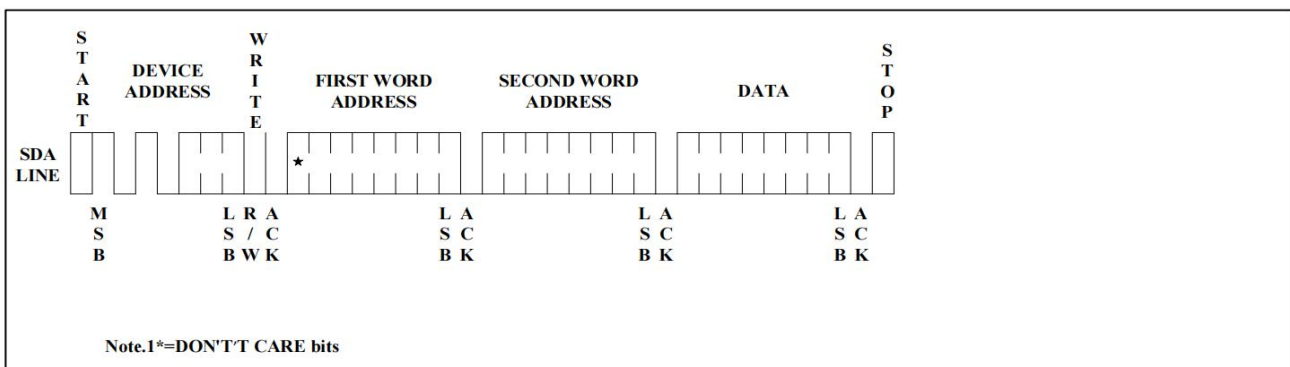




Figure 7. Page Write

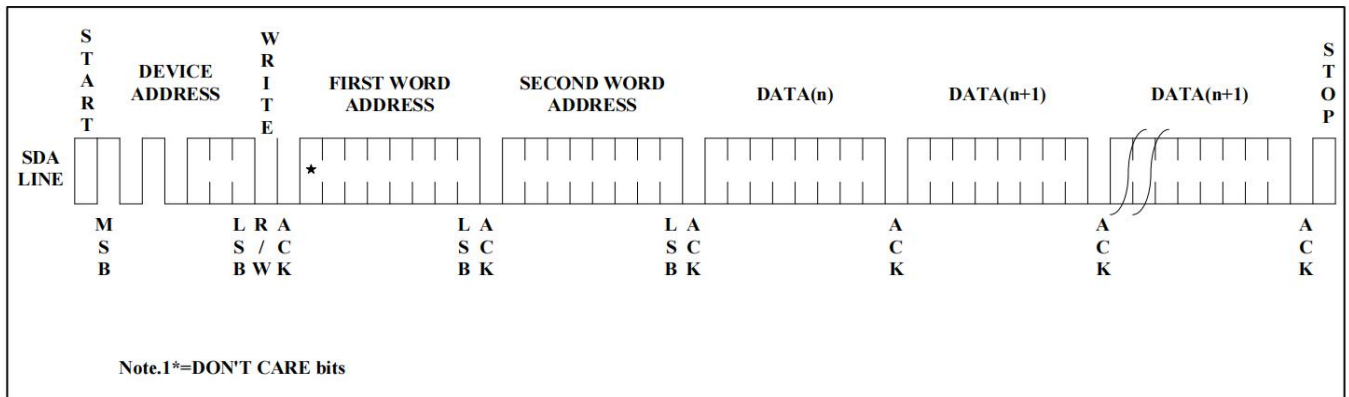


Figure 8. Current Address Read

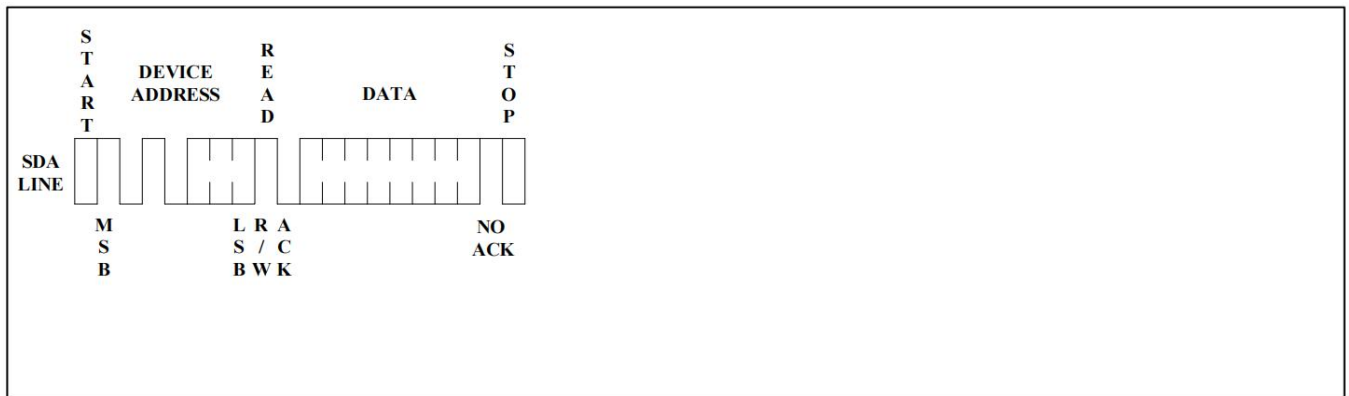


Figure 9. Random Read

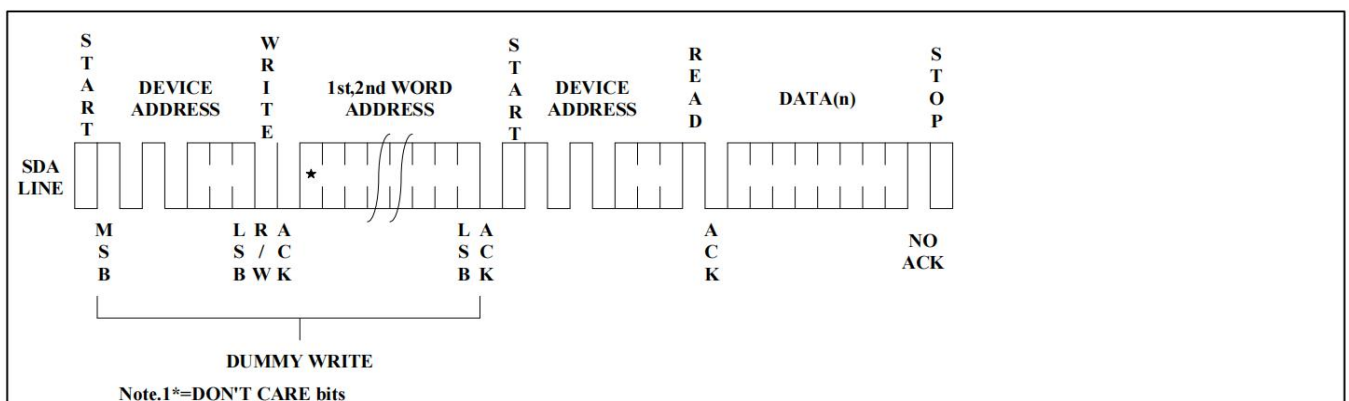
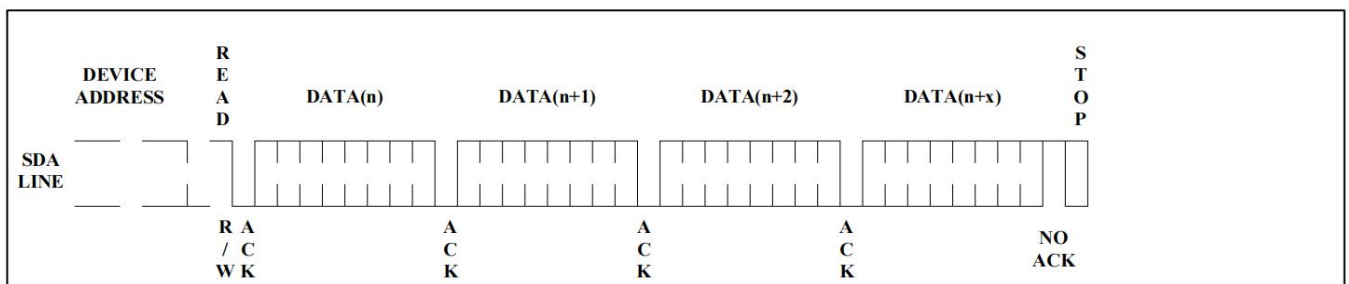


Figure 10. Sequential Read





## Electrical Characteristics

Absolute Maximum Stress Ratings :

- DC Supply Voltage .....-0.3V to +6.5V
- Input / Output Voltage .....GND-0.3V to VCC+0.3V
- Operating Ambient Temperature ..... -40°C to +85°C
- Storage Temperature ..... -65°C to +150°C
- Electrostatic pulse (Human Body model) ..... 8000V

Comments :

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to this device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied or intended. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

## DC Electrical Characteristics

Applicable over recommended operating range from: TA = -40°C to +85°C, VCC = +1.7V to +5.5V (unless otherwise noted)



| Parameter                 | Symbol           | Min                  | Typ  | Max                  | Unit | Condition                                            |
|---------------------------|------------------|----------------------|------|----------------------|------|------------------------------------------------------|
| Supply Voltage            | V <sub>CC1</sub> | 1.7                  | -    | 5.5                  | V    | -                                                    |
| Supply Voltage            | V <sub>CC2</sub> | 2.5                  | -    | 5.5                  | V    | -                                                    |
| Supply Voltage            | V <sub>CC3</sub> | 2.7                  | -    | 5.5                  | V    | -                                                    |
| Supply Voltage            | V <sub>CC4</sub> | 4.5                  | -    | 5.5                  | V    | -                                                    |
| Supply Current VCC=5.0V   | I <sub>CC1</sub> | -                    | 0.4  | 1.0                  | mA   | READ at 400KHZ                                       |
| Supply Current VCC=5.0V   | I <sub>CC2</sub> | -                    | 2.0  | 3.0                  | mA   | WRITE at 400KHZ                                      |
| Supply Current VCC=1.7V   | I <sub>SB1</sub> | -                    | 0.6  | 1.0                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Supply Current VCC=2.5V   | I <sub>SB2</sub> | -                    | 1.0  | 2.0                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Supply Current VCC=2.7V   | I <sub>SB3</sub> | -                    | 1.0  | 2.0                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Supply Current VCC=5.0V   | I <sub>SB4</sub> | -                    | 2.0  | 5.0                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Input Leakage Current     | I <sub>L1</sub>  | -                    | 0.10 | 3.0                  | μA   | V <sub>IN</sub> =V <sub>CC</sub> or V <sub>SS</sub>  |
| Output Leakage Current    | I <sub>LO</sub>  | -                    | 0.05 | 3.0                  | μA   | V <sub>OUT</sub> =V <sub>CC</sub> or V <sub>SS</sub> |
| Input Low Level           | V <sub>IL1</sub> | -0.3                 | -    | V <sub>CC</sub> ×0.3 | V    | V <sub>CC</sub> =1.8V to 5.5V                        |
| Input High Level          | V <sub>IH1</sub> | V <sub>CC</sub> ×0.7 | -    | V <sub>CC</sub> +0.3 | V    | V <sub>CC</sub> =1.8V to 5.5V                        |
| Input Low Level           | V <sub>IL2</sub> | -0.3                 | -    | V <sub>CC</sub> ×0.2 | V    | V <sub>CC</sub> =1.7V                                |
| Input High Level          | V <sub>IH2</sub> | V <sub>CC</sub> ×0.7 | -    | V <sub>CC</sub> +0.3 | V    | V <sub>CC</sub> =1.7V                                |
| Output Low Level VCC=5.0V | V <sub>OL3</sub> | -                    | -    | 0.4                  | V    | I <sub>OL</sub> =3.0mA                               |
| Output Low Level VCC=3.0V | V <sub>OL2</sub> | -                    | -    | 0.4                  | V    | I <sub>OL</sub> =2.1mA                               |
| Output Low Level VCC=1.7V | V <sub>OL1</sub> | -                    | -    | 0.2                  | V    | I <sub>OL</sub> =0.15mA                              |

Table 5

## Pin Capacitance

Applicable over recommended operating range from TA = 25°C, f = 1.0 MHz, VCC = +1.7V

| Parameter                       | Symbol           | Min | Typ | Max | Unit | Condition           |
|---------------------------------|------------------|-----|-----|-----|------|---------------------|
| Input/Output Capacitance(SDA)   | C <sub>I/O</sub> | -   | -   | 8   | pF   | V <sub>IO</sub> =0V |
| Input Capacitance(A0,A1,A2,SCL) | C <sub>IN</sub>  | -   | -   | 6   | pF   | V <sub>IN</sub> =0V |

Table 6

## AC Electrical Characteristics

Applicable over recommended operating range from TA = -40°C to +85°C, VCC = +1.7V to +5.5V, CL = 1 TTL Gate and 100 pF (unless otherwise noted)



| Parameter                                                     | Symbol              | 1.7V ≤ V <sub>CC</sub> < 2.5V |     |     | 2.5V ≤ V <sub>CC</sub> < 5.5V |     |      | Units       |
|---------------------------------------------------------------|---------------------|-------------------------------|-----|-----|-------------------------------|-----|------|-------------|
|                                                               |                     | Min                           | Typ | Max | Min                           | Typ | Max  |             |
| Clock Frequency,SCL                                           | f <sub>SCL</sub>    | -                             | -   | 400 | -                             | -   | 1000 | KHZ         |
| Clock Pulse Width Low                                         | t <sub>LOW</sub>    | 1.2                           | -   | -   | 0.6                           | -   | -    | μs          |
| Clock Pulse Width High                                        | t <sub>HIGH</sub>   | 0.6                           | -   | -   | 0.4                           | -   | -    | μs          |
| Noise Suppression Time                                        | t <sub>i</sub>      | -                             | -   | 50  | -                             | -   | 50   | ns          |
| Clock Low to Data Out Valid                                   | t <sub>AA</sub>     | 0.1                           | -   | 0.9 | 0.05                          | -   | 0.9  | μs          |
| Time the bus must be free before a new transmission can start | t <sub>BUF</sub>    | 1.2                           | -   | -   | 0.5                           | -   | -    | μs          |
| Start Hold Time                                               | t <sub>HD:STA</sub> | 0.6                           | -   | -   | 0.25                          | -   | -    | μs          |
| Start Setup Time                                              | t <sub>SU:DAT</sub> | 0.6                           | -   | -   | 0.25                          | -   | -    | μs          |
| Data In Hold Time                                             | t <sub>HD:DAT</sub> | 0                             | -   | -   | 0                             | -   | -    | μs          |
| Data in Setup Time                                            | t <sub>SU:DAT</sub> | 100                           | -   | -   | 100                           | -   | -    | ns          |
| Input Rise Time(1)                                            | t <sub>r</sub>      | -                             | -   | 0.3 | -                             | -   | 0.3  | μs          |
| Input Fall Time(1)                                            | t <sub>f</sub>      | -                             | -   | 300 | -                             | -   | 300  | μs          |
| Stop Setup Time                                               | t <sub>SU:STO</sub> | 0.6                           | -   | -   | 0.25                          | -   | -    | μs          |
| Data Out Hold Time                                            | t <sub>DH</sub>     | 50                            | -   | -   | 50                            | -   | -    | ns          |
| Write Cycle Time                                              | t <sub>WR</sub>     | -                             | 3.3 | 5   | -                             | 3.3 | 5    | ms          |
| 5.0V,25°C,Byte Mode(1)                                        | Endurance           | 1M                            | -   | -   | -                             | -   | -    | Write Cycle |

Table 7

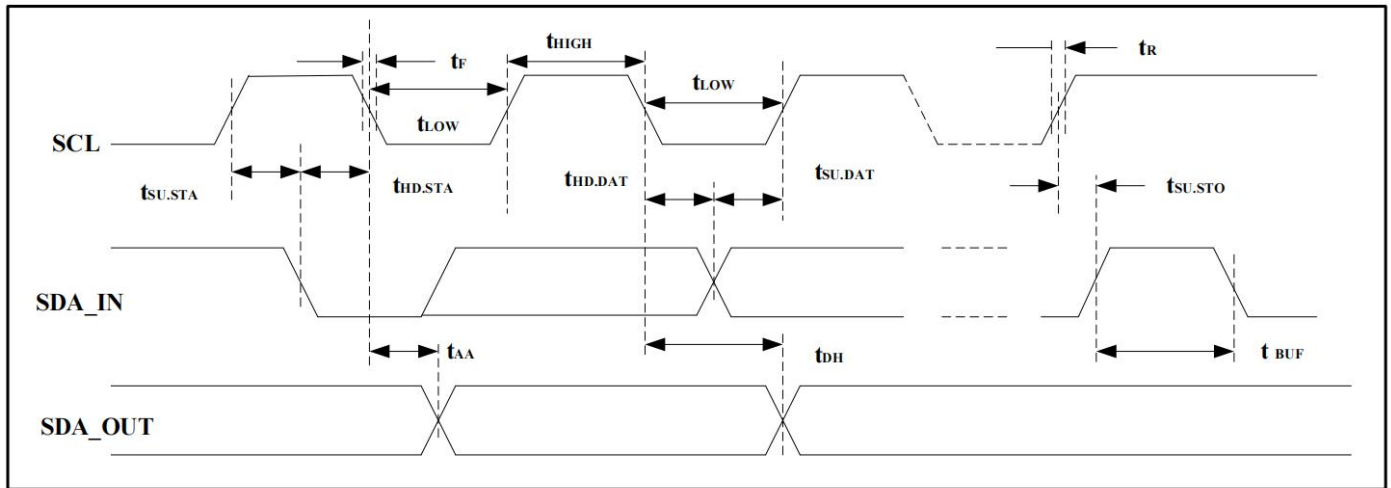
Notes:

1. This parameter is characterized and is not 100% tested.
2. AC measurement conditions:  
 RL (connects to VCC): 1.3 k  
 Input pulse voltages: 0.3 VCC to 0.7 VCC  
 Input rise and fall time: 50 ns  
 Input and output timing reference voltages: 0.5 VCC  
 The value of RL should be concerned according to the actual loading on the user's system.



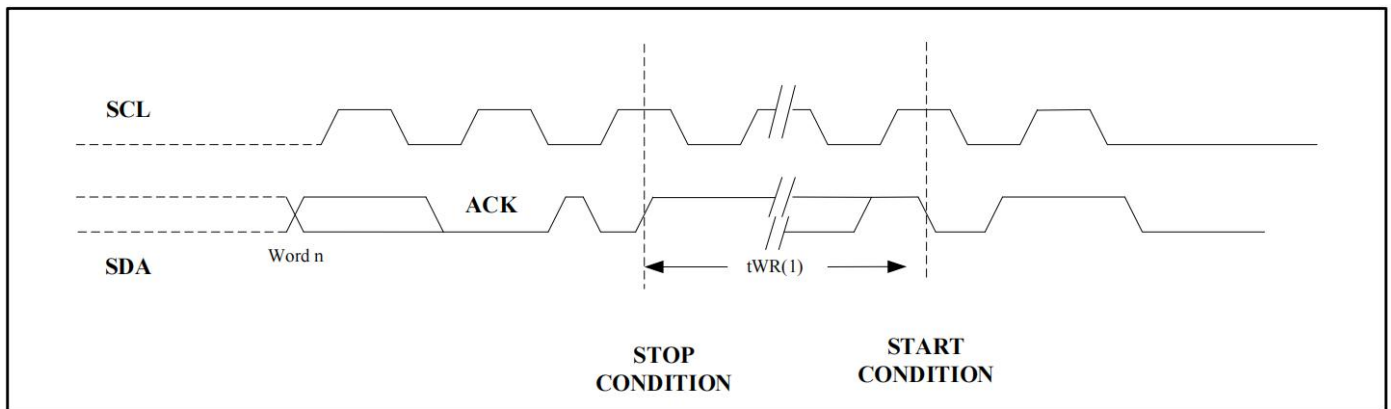
## Bus Timing

Figure 11. SCL: Serial Clock, SDA: Serial Data I/O



## Write Cycle Timing

Figure 12. SCL: Serial Clock, SDA: Serial Data I/O



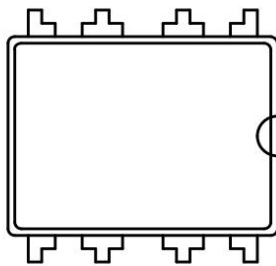
### Notes:

The write cycle time  $t_{WR}$  is the time from a valid stop condition of a write sequence to the end of the internal clear/write cycle.

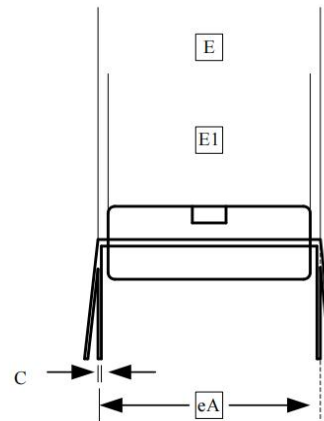


## Package Information

### PDIP Outline Dimensions

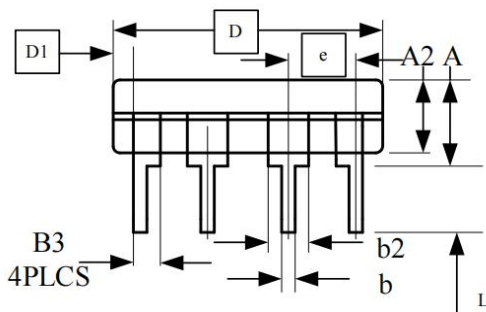


Top View



End View

COMMON DIMENSIONS  
(Unit of Measure=Inches)



Side View

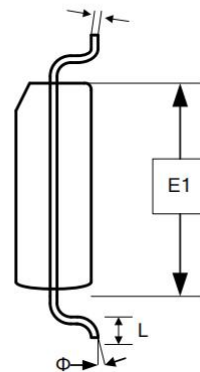
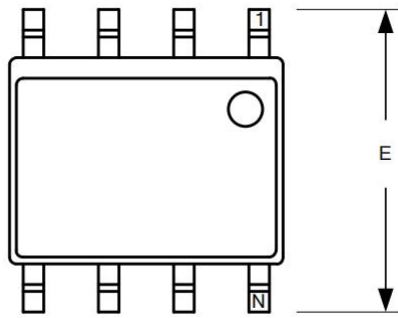
| SYMBOL | MIN      | NOM   | MAX   | NOTE |
|--------|----------|-------|-------|------|
| A      |          |       | 0.210 | 2    |
| A2     | 0.115    | 0.130 | 0.195 |      |
| b      | 0.014    | 0.018 | 0.022 | 5    |
| b2     | 0.045    | 0.060 | 0.070 | 6    |
| b3     | 0.030    | 0.039 | 0.045 | 6    |
| c      | 0.008    | 0.010 | 0.014 |      |
| D      | 0.355    | 0.365 | 0.400 | 3    |
| D1     | 0.005    |       |       | 3    |
| E      | 0.300    | 0.310 | 0.325 | 4    |
| E1     | 0.240    | 0.250 | 0.280 | 3    |
| e      | 0.100BSC |       |       |      |
| eA     | 0.300BSC |       |       | 4    |
| L      | 0.115    | 0.130 | 0.150 | 2    |

#### Notes:

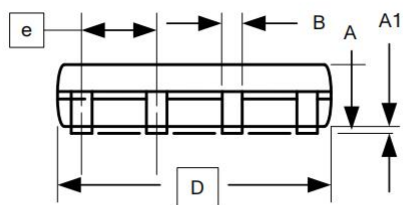
1. This drawing is for general information only; refer to JEDEC Drawing MS-001, Variation BA for additional information.
2. Dimensions A and L are measured with the package seated in JEDEC seating plane Gauge GS-3.
3. D, D1 and E1 dimensions do not include mold Flash or protrusions. Mold Flash or protrusions shall not exceed 0.010 inch.
4. E and eA measured with the leads constrained to be perpendicular to datum.
5. Pointed or rounded lead tips are preferred to ease insertion.
6. b2 and b3 maximum dimensions do not include Dambar protrusions. Dambar protrusions shall not exceed 0.010 (0.25 mm).



SOP



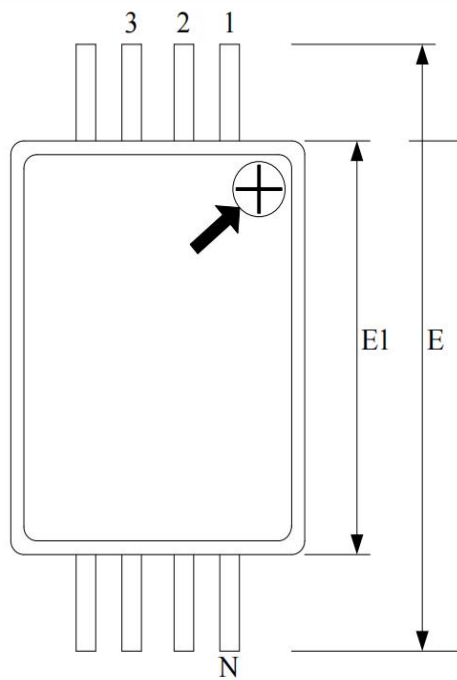
COMMON DIMENSIONS  
(Unit of Measure=mm)



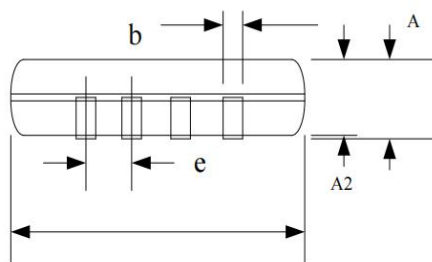
| SYMBOL | MIN     | NOM | MAX  | NOTE |
|--------|---------|-----|------|------|
| A      | 1.35    | —   | 1.75 |      |
| A1     | 0.10    | —   | 0.25 |      |
| b      | 0.31    | —   | 0.51 |      |
| C      | 0.17    | —   | 0.25 |      |
| D      | 4.80    | —   | 5.00 |      |
| E1     | 3.81    | —   | 3.99 |      |
| E      | 5.79    | —   | 6.20 |      |
| e      | 1.27BSC |     |      |      |
| L      | 0.40    | —   | 1.27 |      |
| Φ      | 0"      | —   | 8"   |      |



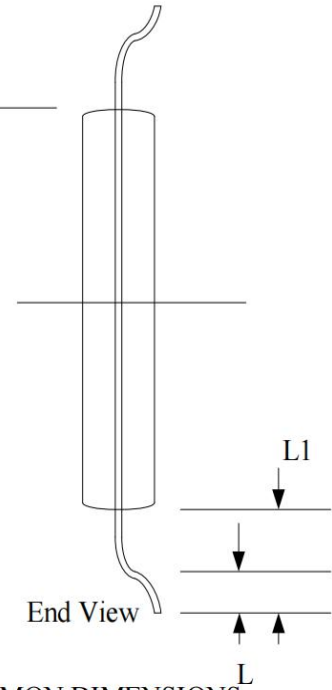
TSSOP



Top View



Side View



End View

COMMON DIMENSIONS  
Unit of Measure=mm

| SYMBOL | MIN     | NOM  | MAX  | NOTE |
|--------|---------|------|------|------|
| D      | 2.90    | 3.00 | 3.10 | 2, 5 |
| E      | 6.40BSC |      |      |      |
| E1     | 4.30    | 4.40 | 4.50 | 3, 5 |
| A      | -       | -    | 1.20 |      |
| A2     | 0.80    | 1.00 | 1.05 |      |
| b      | 0.19    | -    | 0.30 | 4    |
| e      | 0.65BSC |      |      |      |
| L      | 0.45    | 0.60 | 0.75 |      |
| L1     | 1.00REF |      |      |      |

Ordering information



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